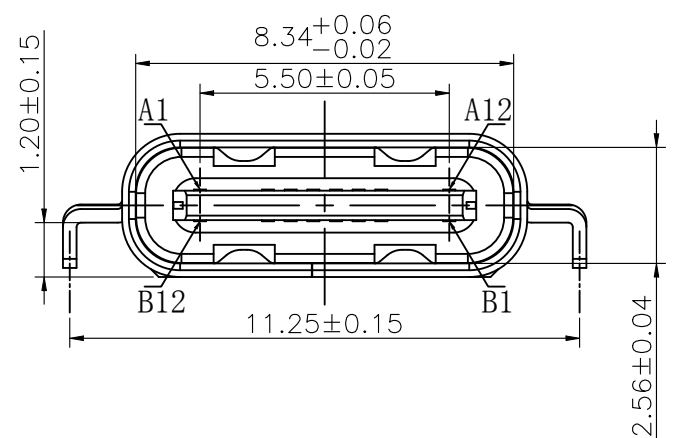
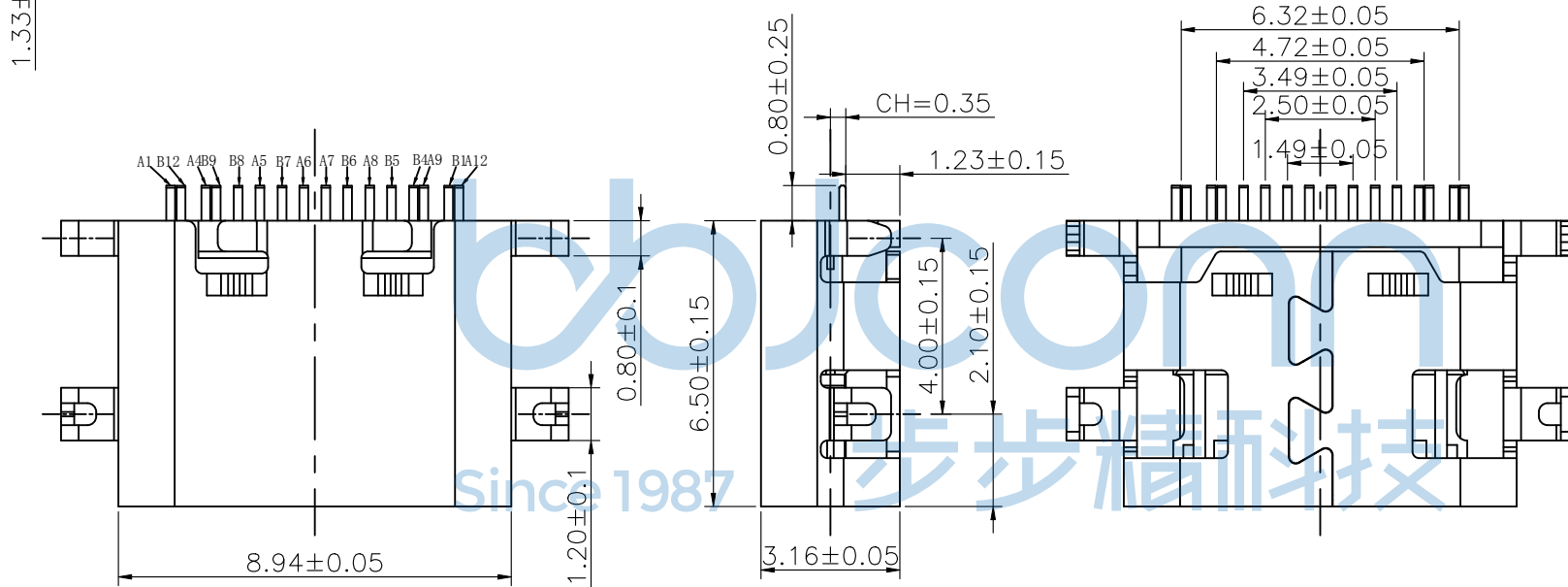
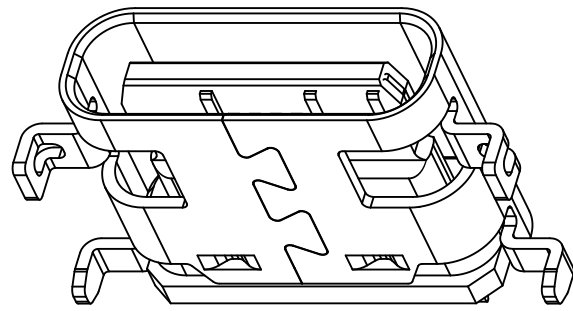
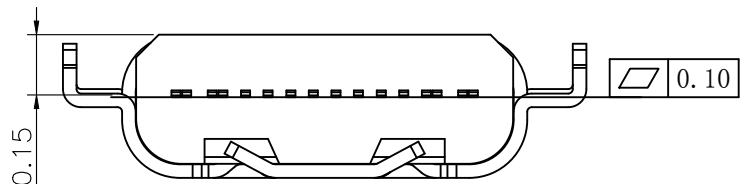


REV.	ECN NO.	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP



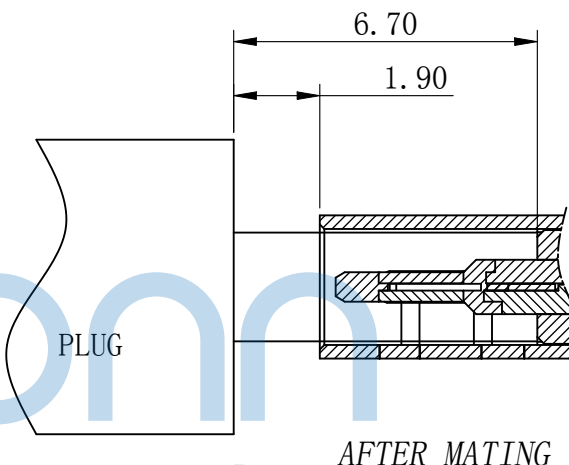
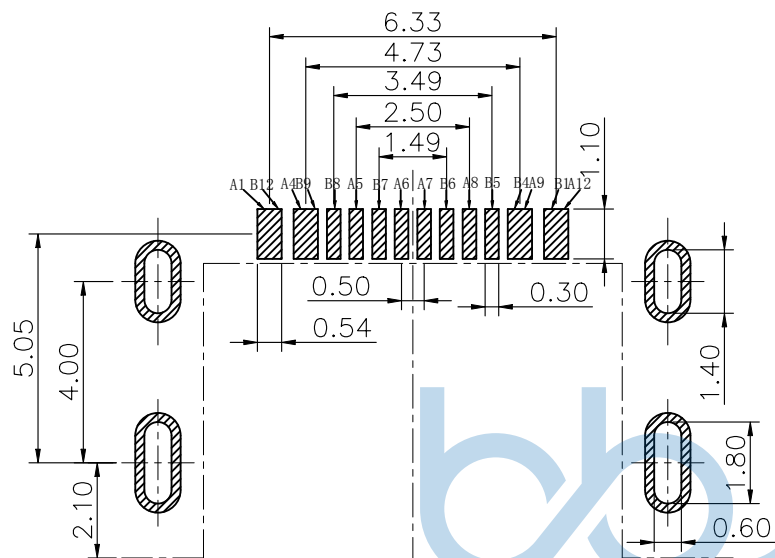
NOTE:

- MATERIAL SPECIFICATION:
 - HOUSING: HIGH TEMPERATURE RESISTANT PLASTIC, UL94 V-0.
 - CONTACTS: COPPER ALLOY
 - MID PLATE: STAINLESS STEEL
 - FRONT SHELL: STAINLESS STEEL
- PLATING SPECIFICATION:
 - CONTACTS:
 - Ni 50u" MIN. UNDER PLATED OVER ALL.
 - Au 1u" PLATED ON THE FUNCTIONAL AREA OF CONTACT. (GOLD PLATING THICKNESS FOLLOW)
 - PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW
 - FRONT SHELL:
 - Ni 30u" MIN. UNDER PLATED OVER ALL.
 - SHIELD PLATE&EMI PLATE:
 - CLEAR ONLY
- MECHANICAL PERFORMANCE,
 - INSERTION FORCE: 0.5~2.0kgf.
 - REMOVAL FORCE: 0.8kgf~2.0kgf.
 - DURABILITY: 10000 CYCLES.
- ELECTRICAL PERFORMANCE,
 - CURRENT RATING: 5.0A
VOLTAGE RATING: 5.0V
 - LLCR:
 - VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.
 - SHIELD: 50mΩ/MAX.
 - LLCR MAX. CHANGE OF ALL PINS: 10mΩ.
 - INSULATION RESISTANCE: 100MΩ MIN
 - DIELECTRIC WITHSTAND VOLTAGE, AC 100V FOR 1 MINUTE.
- ENVIRONMENTAL PERFORMANCE:
 - OPERATING TEMPERATURE: -25° C~+85° C.
- IR REFLOW:
 - THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260° C.



BOM			
序号	名称	用量	品名规格
1	外壳	1	Typec 16PIN 沉板 1.2 外壳 SUS304 T=0.30mm
2	Molding 3	1	Typec 16PIN 沉板 1.2 Molding C7025 T=0.15 PA9T黑色 半成品
2.1	Molding 1	1	Typec 16PIN 沉板 1.2 Molding A C7025 PA9T黑色
2.2	Molding 2	1	Typec 16PIN 沉板 1.2 Molding B C7025 PA9T黑色
2.3	卡勾	1	Typec 16PIN 沉板 卡勾 SUS301 T=0.15mm

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APPD.	JM_Zheng	PJ. NO. : 126-221-160024-N5G SIZE: A4 DRW NO. :	NAME: TYPE-C 16P 母座 四脚插 端子SMT 沉板1.2 L=6.50 CH=0.35 带中夹片 编带
CHKD.	LYX		
PDWG.NO:	0366-2	DR.	TSP
SCALE: N/A		REV. : A0	UNIT: mm
		PAGE: 1/3	



RECOMMENDED PCB LAYOUT (TOP VIEW)

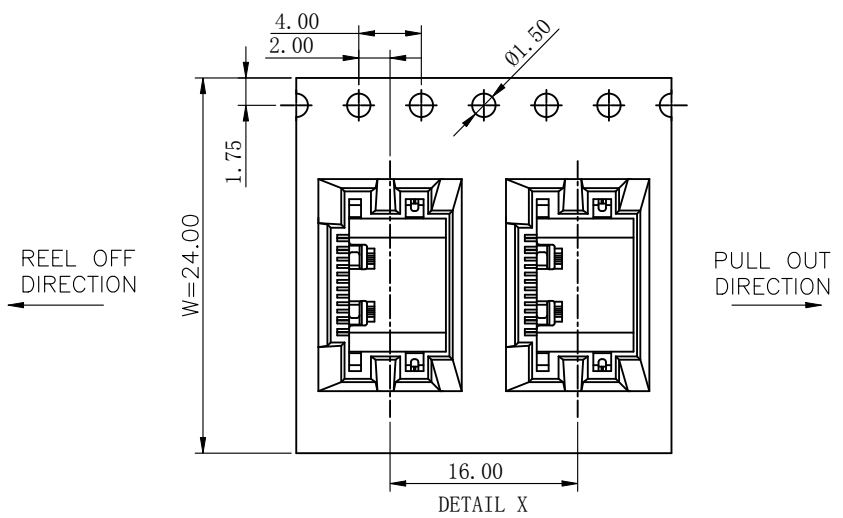
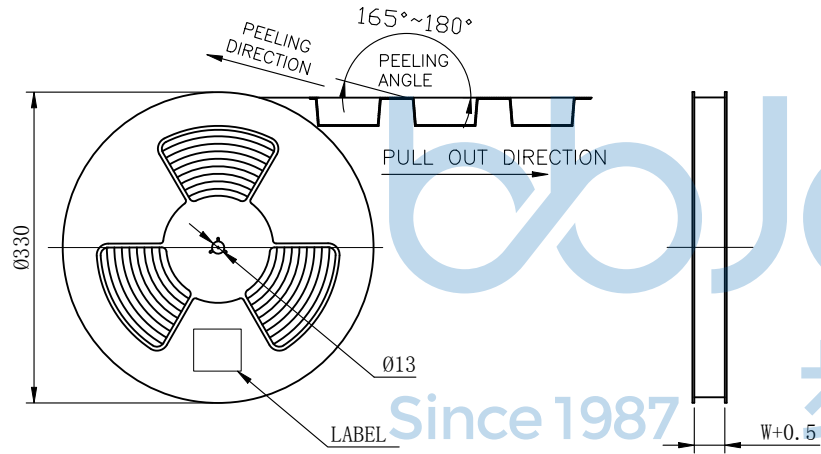
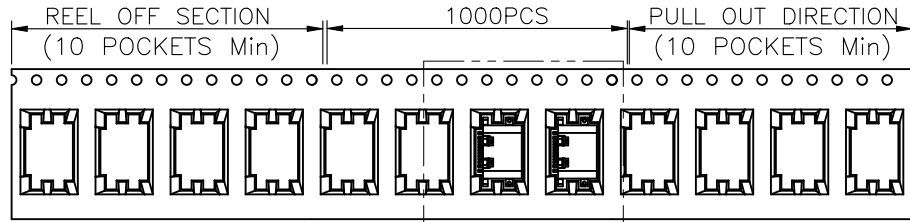
THICKNESS 0.80MM; DEFAULT TOLERANCE: ±0.05

USB TYPE-C PIN ASSIGNMENTS

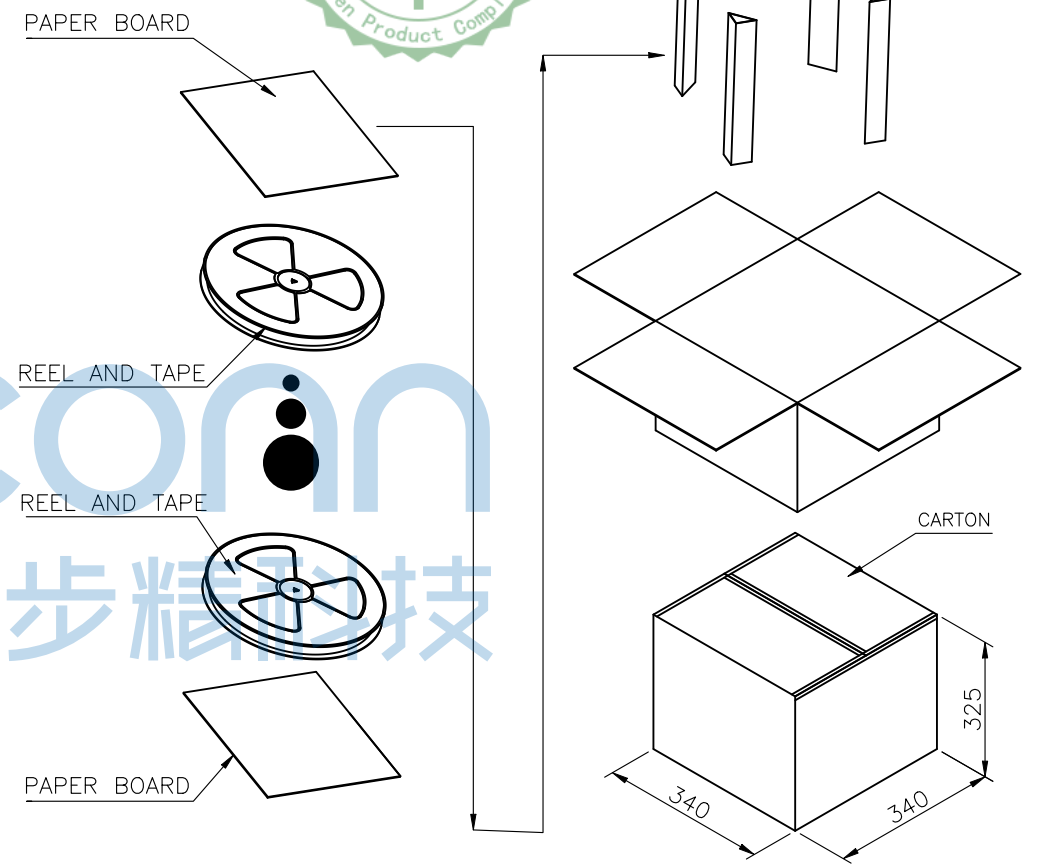
PIN NUMBER	SIGNAL NAME	PIN NUMBER	SIGNAL NAME
A1	GND	B12	GND
A4	V BUS	B9	V BUS
A5	CC1	B8	SBU2
A6	Dp1	B7	Dn2
A7	Dn1	B6	Dp2
A8	SBU1	B5	CC2
A9	V BUS	B4	V BUS
A12	GND	B1	GND

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APPD.	JM_Zheng	P.J. NO.: 126-221-160024-N5G SIZE: A4 DRW NO.:	FINISH: SEE NOTES MAT' L.: SEE NOTES		
CHKD.	LYX		SCALE: N/A REV.: A0 UNIT: mm PAGE: 2/3		
PDWG.NO:	0366-2	DR.	TSP		

REV.	ECN NO.	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP



包装示意图



卷带	规格: ϕ 330mm	包装数量: 1000PCS/盘
纸箱	规格: 340mmX340mmX325mm	包装数量: 10盘 (10000PCS)

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APPD.	JM_Zheng	P.J. NO. : 126-221-160024-N5G SIZE: A4 DRW NO. :	FINISH: SEE NOTES MAT' L. : SEE NOTES
CHKD.	LYX		
PDWG.NO:	0366-2	DR.	TSP
		SCALE: N/A	REV. : A0 UNIT: mm PAGE: 3/3